MIC-6315

OpenVPX CPU Blade with Intel® Xeon® D-1500 family Processor



Features

- 5th Generation Intel® Xeon® processor, up to 12 cores / 24 threads
- Customized from the OpenVPX MOD6-PAY-4F1Q profile
- Default 32GB/16GB DDR4 2133 onboard memory with ECC support, up to 64GR*
- High speed interfaces: Data Plane: Dual SRIO up to 5Gbps, Expansion plane: PCle Gen3, and dual 40GBase-KR4 on user-define plane
- Two ruggedized connectors and common I/O port connectors available on the front panel
- 64GB onboard NAND flash, and 1x SATA M.2, 2x NVME M.2 storage options available



Introduction

The MIC-6315 is the 6U OpenVPX processor blade echoing to the customer's requirements. Based on the Intel® Xeon® D-1500 processor family, the MIC-6315 supports to 12 cores/24 threads, to fulfill the computing requirements form the customer. The MIC-6315 provides various high speed interfaces to communicate with the system: dual Serial Rapid I/O on the Data Plane, a configurable PCle gen. 3 x 16 port on the Expansion Plane, with another x8 and x4 PCie ports on the user-define plane, and there are two 40GBase-KR4 ports available on the user-define plane. These interfaces enable the possibility of high speed data communication to optimize the performance of the product. Serial Rapid I/O and PCI express have low latency, scalable, error recoverable deterministic interconnectivity to the mainstream peripherals and I/O cards to create a system with vast functions.

To maintain the maximum memory throughput in the different harsh environments, the Advantech R&D teams dedicate themselves to optimize the layout of the product. The MIC-6315 is capable to support ECC in a dual channel design running up to 2133MT/s with 64GB capacity*, and has the default capacity of the onboard DDR4 with 32GB or 16GB. The MIC-6315 offers three types of the storage options: A 64GB onboard NAND flash as the native storage, and three M.2 sites with 1x SATA M.2, 2x NVME M.2 interfaces are supported at the same time.

The MIC-6315 has a reinforced convection-cooled heatsink as the thermal solution. Two native ruggedized connectors are available on the front panel, and several common I/O port connectors can be used for debugging purpose at the same time.

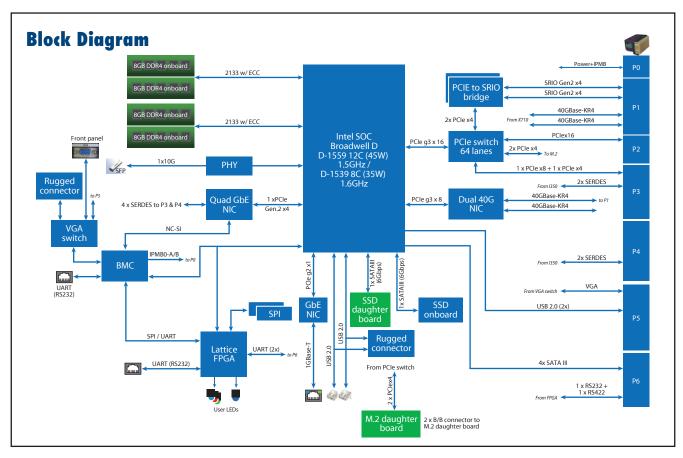
Compliant with the IPMI 2.0, the MIC-6315 uses Adavantech-code-based board management solution, and supports iKVM, remote control and upgrade. This Advantech BMC code uses the LTS kernel for stability and security, and enables the possibility of customization. The user can setup the PCle switch configuration in the BIOS menu without any firmware or hardware modification.

Specifications

	CPU	Intel® XEON® D-1559	
Processor System	Max. Speed	2.1 GHz	
	BIOS	Redundant AMI UEFI based 16MByte SPI flash	
Memory	Technology	Dual channel DDR4 2133MHz w/ ECC	
	Capacity	Default 32GB, up to 64GB with customized BOM*	
	P1	2 x Serial Rapid I/O Gen2 x 4, and 2 x 40GBase-KR4	
	P2	1 x PCle x16 (configurable to 2x 8, 4x4; 1x 8 + 2x 4; 1x 8 + 4x 2)	
VPX Interface	P3	1 x PCle x 8 + 1 x PCle x 4 (configurable to 3x4, 1x8 + 2x2, 2x4 + 2x2, 6x2), 2 x SERDES	
VPA IIILEIIACE	P4	2 x SERDES	
	P5	2 x USB2.0; 1 x VGA	
	P6	4 x SATA3, 1 x RS232, 1 x RS422	
Ethernet	Controller	Intel® 1350-AM4, Intel® XL710BM2 to backplane; 1 x Intel® 1210 to front panel	
	Ruggedized connector	Jonhon HJ30J-36ZKWP7 (36 pins) & HJ30J-18ZKWP7(18 pins)	
	Serial (COM)	1 console (Tx, Rx) to BMC, 1 console (Tx, Rx) to x86 (in the ruggedized connectors)	
Front I/O Interface	Ethernet	1 x RJ-45 10/100/1000BASE-T	
TIOHE I/O HILGHAGE	USB	2x USB 2.0, + 2x USB2.0 in the ruggedized connectors	
	Miscellaneous	1x SFP+ and 1x VGA, the VGA signals are also available in a ruggedized connector in the ruggedized	
		connector	
Operating System	Compatibility	Linux (distribution & Kernel to be confirmed); Windows7, partially support Widows 10	
	Traditional storage	1x SATA III to external M.2, 4x SATA III to backplane	
Storage	High speed storage	2x external NVME M.2	
	Onboard Flash	64G SATA	
Power Requirement	Consumption	90 W total power envelope with D-1559 CPU	
Dhysical Characteristics	PCB Dimensions	5HP, 233.35 x 160 mm (9.2" x 6.3") (W x D)	
Physical Characteristics	Weight	0.95kg without peripherals	

Specifications (Cont.)

		Operating (with 30 CFM airflow)	Non-operating
	Temperature	-40 ~ 55 °C	-55 ~ 105 °C
Environment	Humidity	95% @ 40 °C, non-condensing	95% @ 60 °C, non-condensing
	Shock	VITA 47, OS2 VITA 47, OS1 (convection cooled)	
	Vibration	VITA 47, V2 (conduction cooled) 0.008 g²/Hz, 2 Grms, 5-500Hz (convection coo	oled)
	Altitude	50,000ft @ -40 °C above sea level	
Compliance	VPX	OpenVPX (VITA 65), REDI (VITA 48), IPMI 2.0	
	Safety	FCC class A, CE, RoHS	
	EMC	FCC47 CFR Part15, Class A, CE Mark (EN550	22/EN55024/EN300386)



	Front panel						Main On-board Features	
Part Number	Ruggedized connector		Common connector				CDII	Mamaria
	Pins	Function	USB	Ethernet	SFP+	VGA	CPU	Memory
MIC6315H1A4E-ES	36 (Default) 18 (Reserved)	UART; J-tag; VGA, 2 x USB2.0	2 x USB2.0	1 x RJ-45	1	1	Intel® XEON D-1559	32GB

Ordering Information**

Model number	Configuration
MIC6315H1A4E-ES	MIC-6315 high density computing blade with D-1559

 $[\]ensuremath{^{\star}}\xspace$ For the other configuration availability, please contact your local sales office.

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^{**:} All specification listed above are preliminary, Advantech may modify them without notification because of the test result or business plan